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Dimensions

Chip Size	1210
L	3.2mm +0.3/-0.25mm (0.126 in +0.012/-0.01 in)
W	2.49mm +0.3/-0.25mm (0.098 in +0.012/-0.01 in)
T	2.79mm MAX (0.11 in MAX)
B	0.51mm +/-0.36mm (0.02 in +/-0.014 in)

Packaging Specifications

Packaging	Waffle
Packaging Quantity	80

General Information

Series	SMD MIL COG PRF32535
Style	SMD Chip
Description	SMD, Low ESR, MIL-PRF-32535
RoHS	Yes
Termination	Gold
Failure Rate	N/A
Qualifications	MIL-PRF-32535 T-Level
AEC-Q200	No
Shelf Life	78 Weeks
MSL	1

Specifications

Capacitance	0.027 uF
Capacitance Tolerance	10%
Voltage DC	50 VDC
Dielectric Withstanding Voltage	125 VDC
Temperature Range	-55/+125°C
Temperature Coefficient	COG
Dissipation Factor	0.25% 1 MHz 25C
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	37.04 GOhms

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